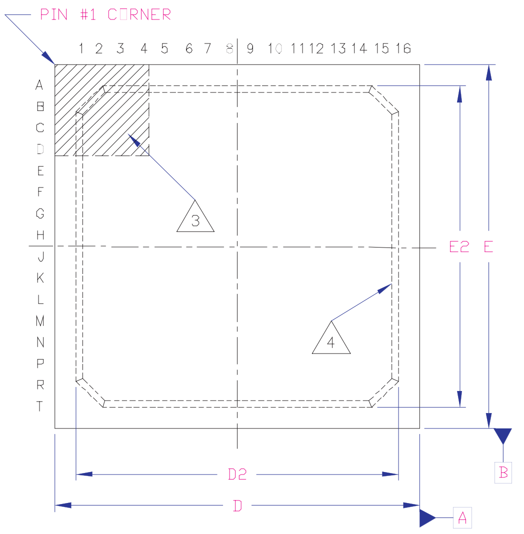
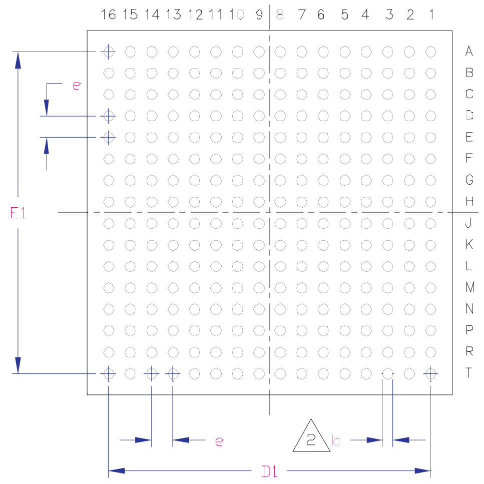
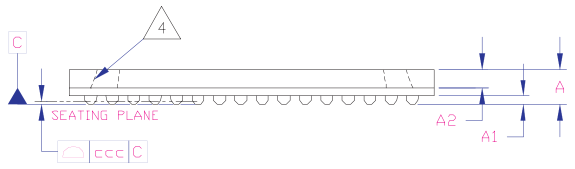
SMSC™
SUCCESS BY DESIGN

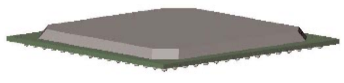
256 LBGA/LBGN PACKAGE OUTLINE



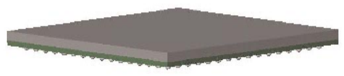




SINGLE (LID) MOLDED



MATRIX MOLDED & SAWED



	Min	Nominal	Max	Remark
A	1.10	-	1.50	Overall Package Height
A1	0.25	-	0.50	Standoff
A2	0.49	-	0.75	Mold Thickness
D	16.80	17.00	17.20	X Board Length
D1	-	15.00	-	X Distance Between End Ball Centers
D2	14.80	15.00	15.20	X Lid Length (see Note 4)
E	16.80	17.00	17.20	Y Board Length
E1	-	15.00	-	Y Distance Between End Ball Centers
E2	14.80	15.00	15.20	Y Lid Length (see Note 4)
b	0.40	0.50	0.70	Ball Diameter
e		1.00 Basic		Pitch
ccc	-	-	0.20	Coplanarity

Notes:

1. Controlling Unit: millimeter.
2. Maximum radial true position tolerance of each ball is 0.125 mm at maximum material condition. Dimension "b (max)" is 0.70mm for all devices, which start production after 2004, and is 0.60mm for all devices, which started production prior to 2005, until the end of their product life.
3. Details of ball A1 identifier are optional but must be located within the zone indicated.
4. Single molded (Lid) version of the package is optional - see dashed line.
5. Provided for reference only - contact your SMSC Regional Sales Office for latest information.

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